

FORM PTO-1595 (modified)

06-26-2002

U.S. DEPARTMENT OF COMMERCE

(Rev. 6-93)

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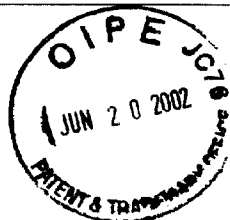
Patent and Trademark Office

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To the Director of the United States Patent and Trademark Office: Please record the attached original documents or copies thereof.

1. Name of conveying party(ies):

Yoshimasa KAWASE



6-20-02

2. Name and address of receiving party(ies):

SEMICONDUCTOR LEADING EDGE TECHNOLOGIES, INC. 16-1 Onogawa, Tsukuba-shi Ibaraki, 305-0053 Japan

Additional conveying party(ies) NO

3. Nature of conveyance:

ASSIGNMENT

Execution Date:

06/04/2002

Additional name(s) & address(es) attached? NO

4. Application number(s) or patent number(s):

If this is being filed together with a new application, the execution date of the application is:

A. Patent Application Number(s):

10/066,783

B. Patent Number(s):

Additional numbers attached? NO

5. Name and address of party to whom correspondence concerning document should be mailed:

William T. Ellis FOLEY & LARDNER Washington Harbour 3000 K Street, N.W., Suite 500 Washington, D.C. 20007-5143

6. Total number of applications/patents involved: 1

7. Total fee (37 C.F.R. § 3.41): \$40.00

X Check Enclosed

Charge to deposit account

8. Deposit account number: 19-0741

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9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. The Commissioner is hereby authorized to charge any additional recordation fees which may be required in this matter to the above-identified deposit account.

William T. Ellis

June 20, 2002

Name of person signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: 2

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Yoshimasa KAWASE

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

Semiconductor Leading Edge Technologies, Inc.
16-1 Onogawa, Tsukuba-shi
Ibaraki, 305-0053
JAPAN

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

for which an application for United States Letters Patent was executed on even date herewith,
(Application No. 10/066,783, filed February 6, 2002),

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the international Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

Yoshimasa Kawase

June 4, 2002

Name: Yoshimasa KAWASE